Product/Process Change Notification

N° 2022-067-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Introduction of an additional pre-assembly location at Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia and introduction of an additional leadframe base material for products in TDSO packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2023-07-17.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46“, which stipulates:
  “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
  Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal address D-81726 München Internet www.infineon.com Headquarters Am Campeon 1-15, D-85579 Neubiberg Phone +49 (0)89 234-0
Chairman of the Supervisory Board Dr. Herbert Diess
Management Board Jochen Hanebeck (CEO), Constanze Hufenbecher, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg
Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

Product/Process Change Notification

N° 2022-067-A

Products affected	Please refer to attached affected product list PCN_2022-067-A_[customer-no].pdf

Detailed change information

Subject:	Introduction of an additional pre-assembly location at Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia and introduction of an additional leadframe base material for products in TDSO packages
Reason/Motivation:	To assure continuity of supply and enable flexible manufacturing, pre-assembly production is expanded and the new base material used for leadframes is introduced.

Description	**Old**	**New**
PROCESS - ASSEMBLY: Change of leadframe base material	For TDSO-8 packages only Raw material supplier for leadframes: A	For TDSO-8 packages only Raw material suppliers for leadframes: A & B
PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site	Pre-Assembly production site: Infineon Technologies AG (Regensburg), Regensburg, Germany	Pre-Assembly production sites: Infineon Technologies AG (Regensburg), Regensburg, Germany and Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia

Product identification	Traceability assured via date code. No change in SP ordering number.
Anticipated impact of change	Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form. DeQuMa-ID(s): SEM-PA-02 / SEM-PA-18

Attachments		
	PCN_2022-067-A_[customer-no].pdf	affected product list
	3_cip22067_A	customer information package, available upon request

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2023-12-06
Last order date (LOD) [2]	2023-12-06
Last delivery date (LDD) [3]	2024-12-06

[1] Provided date or earlier after customer approval.
[2] Last date where orders for unchanged products will be accepted.
[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

If you have any questions, please do not hesitate to contact your local sales office.

PCN 2022-067-A

Introduction of an additional pre-assembly location at Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia and introduction of an additional leadframe base material for products in TDSO packages

Affected products sold to FUTURE ELECTRONICS INC. (4048203)

Sales name	SP number	OPN	Package	Customer part number
TLE4998P8	SP000902772	TLE4998P8XUMA1	PG-TDSO-8-1	